

* * * * * STN Columbus * * * * *

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COST IN U.S. DOLLARS

SINCE FILE

TOTAL

ENTRY

SESSION

FULL ESTIMATED COST

0.21

0.21

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FILE 'USPAT2' ENTERED AT 11:52:50 ON 15 FEB 2007

CA INDEXING COPYRIGHT (C) 2007 AMERICAN CHEMICAL SOCIETY (ACS)

=> s microcapsule and dispers? and colored particle#

L1 359 MICROCAPSULE AND DISPERS? AND COLORED PARTICLE#

=> s l1 and oil phase#

L2 97 L1 AND OIL PHASE#

=> s l2 and wall encapsulat?

L3 3 L2 AND WALL ENCAPSULAT?

=> d l3 1-3

L3 ANSWER 1 OF 3 USPATFULL on STN

AN 2005:151035 USPATFULL

TI Microcapsules and processes for producing the same

IN Hayashi, Masaki, Okayama-shi, JAPAN

PA Daicel Chemical Industries, Ltd. (non-U.S. corporation)

PI US 2005129946 A1 20050616

AI US 2004-7233 A1 20041209 (11)

PRAI JP 2003-412684 20031211

DT Utility

FS APPLICATION

LN.CNT 1793

INCL INCLM: 428/402.200

INCLS: 427/213.300

NCL NCLM: 428/402.200

NCLS: 427/213.300

IC [7]

ICM G03C008-00

ICS B32B009-00

IPCI G03C0008-00 [ICM,7]; B32B0009-00 [ICS,7]

IPCR B01J0013-04 [I,C*]; B01J0013-04 [I,A]; B01J0013-06 [I,C*];

B01J0013-16 [I,A]; B32B0009-00 [I,C*]; B32B0009-00 [I,A];
G02F0001-01 [I,C*]; G02F0001-13 [I,C*]; G02F0001-1334 [I,A];
G02F0001-19 [I,A]; G03C0007-392 [I,C*]; G03C0007-392 [I,A];
G03C0008-00 [I,C*]; G03C0008-00 [I,A]; G03G0005-00 [I,C*];
G03G0005-00 [I,A]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L3 ANSWER 2 OF 3 USPATFULL on STN
AN 2004:252198 USPATFULL
TI Microcapsules and processes for producing the same
IN Hayashi, Masaki, Okayama-shi, JAPAN
Furomoto, Mitsuru, Kakogawa-shi, JAPAN
PI US 2004195711 A1 20041007
AI US 2004-800866 A1 20040316 (10)
PRAI JP 2003-86233 20030326
JP 2003-412685 20031211
DT Utility
FS APPLICATION
LN.CNT 1923
INCL INCLM: 264/004.100
INCLS: 264/004.300
NCL NCLM: 264/004.100
NCLS: 264/004.300
IC [7]
ICM B01J013-02
ICS B01J013-04; B01J013-20
IPCI B01J0013-02 [ICM,7]; B01J0013-04 [ICS,7]; B01J0013-20 [ICS,7]
IPCR G02F0001-01 [I,C*]; G02F0001-167 [I,A]; B01J0013-04 [I,C*];
B01J0013-04 [I,A]; B01J0013-06 [I,C*]; B01J0013-14 [I,A]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L3 ANSWER 3 OF 3 USPATFULL on STN
AN 2004:124455 USPATFULL
TI ELECTROPHORETIC MEDIA CONTAINING SPECULARLY REFLECTIVE PARTICLES
IN Pullen, Anthony Edward, 95 Hull Street, Belmont, MA, UNITED STATES
02478
Duthaler, Gregg M., 40 Dunster Road, Needham, MA, UNITED STATES 02494
Amundson, Karl R., 91 Trowbridge Street, Apartment No. 21, Cambridge,
MA, UNITED STATES 02138
Davis, Benjamin Max, 290 Pennsylvania Avenue, Apartment No. 2, San
Francisco, CA, UNITED STATES 94107
PA E INK CORPORATION, Cambridge, MA, UNITED STATES (U.S. corporation)
PI US 2004094422 A1 20040520
AI US 2003-604638 A1 20030806 (10)
PRAI US 2002-319453P 20020807 (60)
DT Utility
FS APPLICATION
LN.CNT 1687
INCL INCLM: 204/600.000
INCLS: 204/616.000
NCL NCLM: 204/600.000
NCLS: 204/616.000
IC [7]
ICM C25B013-00
ICS G01N027-27
IPCI C25B0013-00 [ICM,7]; G01N0027-27 [ICS,7]
IPCR G01N0027-447 [I,C*]; G01N0027-447 [I,A]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

=> s 12 and wall and anionic resin#

L4 2 L2 AND WALL AND ANIONIC RESIN#

=> s 14 and free acid

L5 2 L4 AND FREE ACID

=> d 15 1-2

L5 ANSWER 1 OF 2 USPATFULL on STN

AN 2005:151035 USPATFULL

TI Microcapsules and processes for producing the same

IN Hayashi, Masaki, Okayama-shi, JAPAN

PA Daicel Chemical Industries, Ltd. (non-U.S. corporation)

PI US 2005129946 A1 20050616

AI US 2004-7233 A1 20041209 (11)

PRAI JP 2003-412684 20031211

DT Utility

FS APPLICATION

LN.CNT 1793

INCL INCLM: 428/402.200

INCLS: 427/213.300

NCL NCLM: 428/402.200

NCLS: 427/213.300

IC [7]

ICM G03C008-00

ICS B32B009-00

IPCI G03C0008-00 [ICM,7]; B32B0009-00 [ICS,7]

IPCR B01J0013-04 [I,C*]; B01J0013-04 [I,A]; B01J0013-06 [I,C*];

B01J0013-16 [I,A]; B32B0009-00 [I,C*]; B32B0009-00 [I,A];

G02F0001-01 [I,C*]; G02F0001-13 [I,C*]; G02F0001-1334 [I,A];

G02F0001-19 [I,A]; G03C0007-392 [I,C*]; G03C0007-392 [I,A];

G03C0008-00 [I,C*]; G03C0008-00 [I,A]; G03G0005-00 [I,C*];

G03G0005-00 [I,A]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

L5 ANSWER 2 OF 2 USPATFULL on STN

AN 2004:252198 USPATFULL

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IN Hayashi, Masaki, Okayama-shi, JAPAN

Furomoto, Mitsuru, Kakogawa-shi, JAPAN

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AI US 2004-800866 A1 20040316 (10)

PRAI JP 2003-86233 20030326

JP 2003-412685 20031211

DT Utility

FS APPLICATION

LN.CNT 1923

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INCLS: 264/004.300

NCL NCLM: 264/004.100

NCLS: 264/004.300

IC [7]

ICM B01J013-02

ICS B01J013-04; B01J013-20

IPCI B01J0013-02 [ICM,7]; B01J0013-04 [ICS,7]; B01J0013-20 [ICS,7]

IPCR G02F0001-01 [I,C*]; G02F0001-167 [I,A]; B01J0013-04 [I,C*];

B01J0013-04 [I,A]; B01J0013-06 [I,C*]; B01J0013-14 [I,A]

CAS INDEXING IS AVAILABLE FOR THIS PATENT.

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